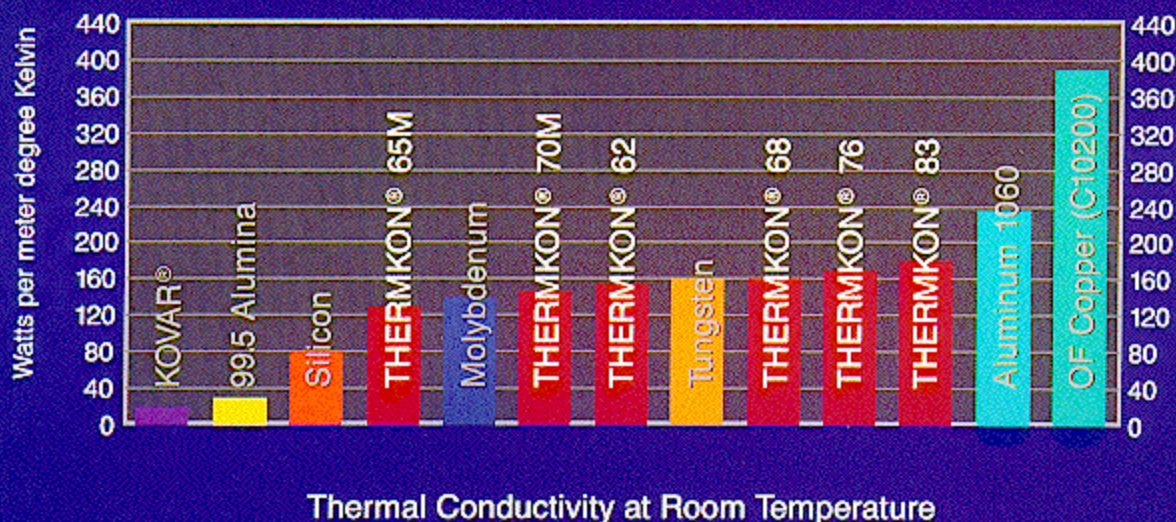
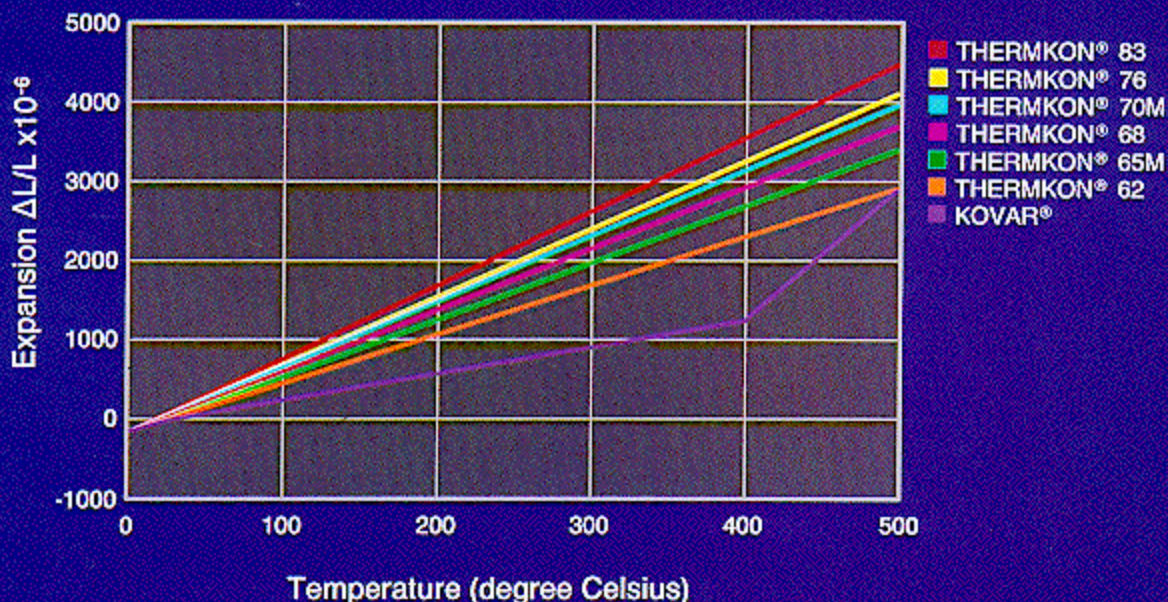


## THERMAL CONDUCTIVITY OF VARIOUS METALS AND CERAMICS



The Thermal Conductivity of the Thermkon® composite materials ranges from 135 w/m/K to 190 w/m/K. Thermkon®'s thermal conductivity is higher than silicon and significantly higher than the traditional low expansion alloys.

## THERMAL EXPANSION FOR VARIOUS HEAT SINK MATERIALS



All Thermkon® materials offer controlled rates of thermal expansion, closely matching those of alumina and beryllium oxide ceramics over a wide range of temperatures. This facilitates joining and reduces detrimental stress in the microelectronics package. These close coefficients may allow the designer to use thinner ceramic substrates in the packaging system.